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**Semiconductor devices – Micro-electromechanical devices –
Part 28: Performance testing method of vibration-driven MEMS electret energy
harvesting devices**

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MICRO-ELECTROMECHANICAL DEVICES –**
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Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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**SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –**

**Part 28: Performance testing method of vibration-driven
MEMS electret energy harvesting devices**

1 Scope

This part of IEC 62047 specifies terms and definitions, and a performance testing method of vibration driven MEMS electret energy harvesting devices to determine the characteristic parameters for consumer, industry or any application.

This document applies to vibration driven electret energy harvesting devices whose electrodes with a gap below 1 000 μm are covered by dielectric material with trapped charges and are fabricated by MEMS processes such as etching, photolithography or deposition.

2 Normative references

There are no normative references in this document.